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Dual Long-Tailed Pair Transistor Array

The HFA3102 is an all NPN transistor array configured as dual differential amplifiers with tail transistors. Based on Intersil bonded wafer UHF-1 SOI process, this array achieves very high f_T (10GHz) while maintaining excellent h_{FE} and V_{BE} matching characteristics over temperature. Collector leakage currents are maintained to under 0.01nA.

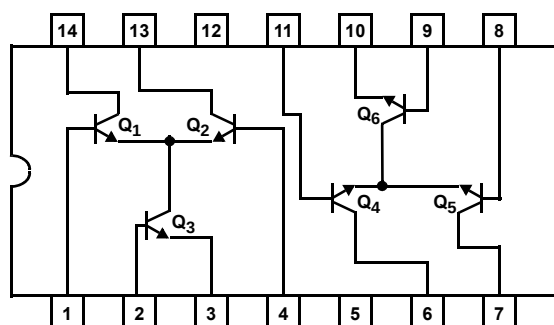
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
HFA3102B96	-40 to 85	14 Ld SOIC Tape and Reel	M14.15
HFA3102BZ (Note)	-40 to 85	14 Ld SOIC (Pb-free)	M14.15
HFA3102BZ96 (Note)	-40 to 85	14 Ld SOIC Tape and Reel (Pb-free)	M14.15

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Pinout/Functional Diagram

HFA3102 (SOIC)
TOP VIEW



Features

- High Gain-Bandwidth Product (f_T) 10GHz
- High Power Gain-Bandwidth Product. 5GHz
- High Current Gain (h_{FE}) 70
- Noise Figure (Transistor) 3.5dB
- Low Collector Leakage Current <0.01nA
- Excellent h_{FE} and V_{BE} Matching
- Pin-to-Pin to UPA102G
- Pb-Free Plus Anneal Available (RoHS Compliant)

Applications

- Single Balanced Mixers
- Wide Band Amplification Stages
- Differential Amplifiers
- Multipliers
- Automatic Gain Control Circuits
- Frequency Doublers, Triplers
- Oscillators
- Constant Current Sources
- Wireless Communication Systems
- Radio and Satellite Communications
- Fiber Optic Signal Processing
- High Performance Instrumentation

HFA3102

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$

V_{CEO} Collector to Emitter Voltage	8.0V
V_{CBO} Collector to Base Voltage	12.0V
V_{EBO} Emitter to Base Voltage	12.0V
I_C , Collector Current	30mA

Operating Conditions

Temperature Range	-40°C to 85°C
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Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} ($^\circ\text{C}/\text{W}$)
SOIC Package	128
Maximum Power Dissipation at 75°	
Any One Transistor	0.25W
Maximum Junction Temperature (Die)	175°C
Maximum Junction Temperature (Plastic Package)	150°C
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications $T_A = 25^\circ\text{C}$

SYMBOLS	PARAMETER	TEST CONDITIONS	(NOTE 2) TEST LEVEL	ALL GRADES			UNITS
				MIN	TYP	MAX	
$V_{(BR)CBO}$	Collector-to-Base Breakdown Voltage (Q_1 , Q_2 , Q_4 , and Q_5)	$I_C = 100\mu\text{A}$, $I_E = 0$	A	12	18	-	V
$V_{(BR)CEO}$	Collector-to-Emitter Breakdown Voltage (Q_1 thru Q_6)	$I_C = 100\mu\text{A}$, $I_B = 0$	A	8	12	-	V
$V_{(BR)EBO}$	Emitter-to-Base Breakdown Voltage (Q_3 and Q_6)	$I_E = 50\mu\text{A}$, $I_C = 0$	A	5.5	6	-	V
I_{CBO}	Collector Cutoff Current (Q_1 , Q_2 , Q_4 , and Q_5)	$V_{CB} = 5\text{V}$, $I_E = 0$	A	-	0.1	10	μA
I_{EBO}	Emitter Cutoff Current (Q_3 and Q_6)	$V_{EB} = 1\text{V}$, $I_C = 0$	A	-	-	100	μA
h_{FE}	DC Current Gain (Q_1 thru Q_6)	$I_C = 10\text{mA}$, $V_{CE} = 3\text{V}$	A	40	70	-	-
C_{CB}	Collector-to-Base Capacitance	$V_{CB} = 5\text{V}$, $f = 1\text{MHz}$	B	-	300	-	fF
C_{EB}	Emitter-to-Base Capacitance	$V_{EB} = 0$, $f = 1\text{MHz}$	B	-	200	-	fF
f_T	Current Gain-Bandwidth Product	$I_C = 10\text{mA}$, $V_{CE} = 5\text{V}$	C	-	10	-	GHz
f_{MAX}	Power Gain-Bandwidth Product	$I_C = 10\text{mA}$, $V_{CE} = 5\text{V}$	C	-	5	-	GHz
G_{NFMIN}	Available Gain at Minimum Noise Figure	$I_C = 3\text{mA}$, $V_{CE} = 3\text{V}$	$f = 0.5\text{GHz}$ C $f = 1.0\text{GHz}$ C	-	17.5 12.4	-	dB dB
NF_{MIN}	Minimum Noise Figure	$I_C = 3\text{mA}$, $V_{CE} = 3\text{V}$	$f = 0.5\text{GHz}$ C $f = 1.0\text{GHz}$ C	-	1.8 2.1	-	dB dB
$NF_{50\Omega}$	50 Ω Noise Figure	$I_C = 3\text{mA}$, $V_{CE} = 3\text{V}$	$f = 0.5\text{GHz}$ C $f = 1.0\text{GHz}$ C	-	3.3 3.5	-	dB dB
h_{FE1}/h_{FE2}	DC Current Gain Matching (Q_1 and Q_2 , Q_4 and Q_5)	$I_C = 10\text{mA}$, $V_{CE} = 3\text{V}$	A	0.9	1.0	1.1	-
V_{OS}	Input Offset Voltage (Q_1 and Q_2), (Q_4 and Q_5)	$I_C = 10\text{mA}$, $V_{CE} = 3\text{V}$	A	-	1.5	5	mV
I_{OS}	Input Offset Current (Q_1 and Q_2), (Q_4 and Q_5)	$I_C = 10\text{mA}$, $V_{CE} = 3\text{V}$	A	-	5	25	μA
dV_{OS}/dT	Input Offset Voltage TC (Q_1 and Q_2 , Q_4 and Q_5)	$I_C = 10\text{mA}$, $V_{CE} = 3\text{V}$	C	-	0.5	-	$\mu\text{V}/^\circ\text{C}$
$I_{TRENCH-LEAKAGE}$	Collector-to-Collector Leakage (Pin 6, 7, 13, and 14)	$\Delta V_{TEST} = 5\text{V}$	B	-	0.01	-	nA

NOTE:

- Test Level: A. Production Tested; B. Typical or Guaranteed Limit Based on Characterization; C. Design Typical for Information Only

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PSPICE Model for a Single Transistor

.Model NUHFARRY NPN

+ (IS= 1.840E-16 XTI= 3.000E+00 EG= 1.110E+00
VAF= 7.200E+01
+ VAR= 4.500E+00 BF= 1.036E+02 ISE= 1.686E-19
NE= 1.400E+00
+ IKF= 5.400E-02 XTB= 0.000E+00 BR= 1.000E+01
ISC= 1.605E-14
+ NC= 1.800E+00 IKR= 5.400E-02 RC= 1.140E+01
CJC= 3.980E-13
+ MJC= 2.400E-01 VJC= 9.700E-01 FC= 5.000E-01
CJE= 2.400E-13
+ MJE= 5.100E-01 VJE= 8.690E-01 TR= 4.000E-09
TF= 10.51E-12
+ ITF= 3.500E-02 XTF= 2.300E+00 VTF= 3.500E+00
PTF= 0.000E+00
+ XCJC= 9.000E-01 CJS= 1.689E-13 VJS= 9.982E-01
MJS= 0.000E+00
+ RE= 1.848E+00 RB= 5.007E+01 RBM= 1.974E+00
KF= 0.000E+00
+ AF= 1.000E+00)

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Common Emitter S-Parameters

$V_{CE} = 5V$ and $I_C = 5mA$

FREQ. (Hz)	S ₁₁	PHASE(S ₁₁)	S ₁₂	PHASE(S ₁₂)	S ₂₁	PHASE(S ₂₁)	S ₂₂	PHASE(S ₂₂)
1.0E+08	0.833079	-11.7873	1.418901E-02	78.8805	11.0722	168.576	0.976833	-11.0509
2.0E+08	0.791776	-22.8290	2.695740E-02	68.6355	10.5177	157.897	0.930993	-21.3586
3.0E+08	0.734911	-32.6450	3.750029E-02	59.5861	9.75379	148.443	0.868128	-30.4451
4.0E+08	0.672811	-41.0871	4.572138E-02	51.9018	8.91866	140.361	0.799886	-38.1641
5.0E+08	0.612401	-48.2370	5.194147E-02	45.5043	8.10511	133.569	0.734033	-44.5998
6.0E+08	0.557126	-54.2780	5.659943E-02	40.2112	7.35944	127.882	0.674392	-49.9370
7.0E+08	0.508133	-59.4102	6.009507E-02	35.8226	6.69712	123.102	0.622181	-54.3777
8.0E+08	0.465361	-63.8123	6.274213E-02	32.1594	6.11750	119.047	0.577269	-58.1022
9.0E+08	0.428238	-67.6313	6.477134E-02	29.0743	5.61303	115.571	0.538952	-61.2587
1.0E+09	0.396034	-70.9834	6.634791E-02	26.4506	5.17405	112.556	0.506365	-63.9647
1.1E+09	0.368032	-73.9591	6.758932E-02	24.1974	4.79104	109.913	0.478663	-66.3116
1.2E+09	0.343589	-76.6285	6.857937E-02	22.2441	4.45546	107.570	0.455091	-68.3702
1.3E+09	0.322155	-79.0462	6.937837E-02	20.5358	4.15997	105.472	0.435008	-70.1958
1.4E+09	0.303268	-81.2548	7.003020E-02	19.0293	3.89845	103.576	0.417872	-71.8314
1.5E+09	0.286542	-83.2880	7.056718E-02	17.6908	3.66577	101.849	0.403238	-73.3108
1.6E+09	0.271660	-85.1723	7.101343E-02	16.4930	3.45770	100.262	0.390735	-74.6609
1.7E+09	0.258359	-86.9292	7.138717E-02	15.4143	3.27074	98.7956	0.380056	-75.9030
1.8E+09	0.246420	-88.5759	7.170231E-02	14.4370	3.10197	97.4307	0.370947	-77.0544
1.9E+09	0.235659	-90.1265	7.196964E-02	13.5469	2.94897	96.1533	0.363195	-78.1288
2.0E+09	0.225923	-91.5925	7.219757E-02	12.7319	2.80969	94.9515	0.356623	-79.1377
2.1E+09	0.217085	-92.9836	7.239274E-02	11.9824	2.68243	93.8156	0.351081	-80.0903
2.2E+09	0.209034	-94.3076	7.256046E-02	11.2901	2.56573	92.7373	0.346442	-80.9942
2.3E+09	0.201678	-95.5713	7.270498E-02	10.6480	2.45837	91.7097	0.342599	-81.8557
2.4E+09	0.194939	-96.7803	7.282977E-02	10.0503	2.35928	90.7271	0.339458	-82.6802
2.5E+09	0.188747	-97.9395	7.293764E-02	9.49212	2.26756	89.7844	0.336942	-83.4719
2.6E+09	0.183044	-99.0530	7.303093E-02	8.96908	2.18243	88.8775	0.334982	-84.2347
2.7E+09	0.177780	-100.124	7.311157E-02	8.47753	2.10322	88.0026	0.333518	-84.9716
2.8E+09	0.172909	-101.156	7.318117E-02	8.01430	2.02934	87.1565	0.332499	-85.6853
2.9E+09	0.168394	-102.152	7.324107E-02	7.57661	1.96027	86.3366	0.331879	-86.3781
3.0E+09	0.164200	-103.114	7.329243E-02	7.16204	1.89556	85.5404	0.331620	-87.0518

$V_{CE} = 5V$ and $I_C = 10mA$

FREQ. (Hz)	S ₁₁	PHASE(S ₁₁)	S ₁₂	PHASE(S ₁₂)	S ₂₁	PHASE(S ₂₁)	S ₂₂	PHASE(S ₂₂)
1.0E+08	0.728106	-16.4319	1.273920E-02	75.4177	15.1273	165.227	0.959692	-14.2688
2.0E+08	0.670836	-31.2669	2.342300E-02	62.8941	13.9061	152.045	0.886232	-26.9507
3.0E+08	0.600268	-43.7663	3.132521E-02	52.5891	12.3970	141.185	0.796016	-37.3172
4.0E+08	0.531768	-54.0028	3.681579E-02	44.5019	10.9257	132.570	0.708892	-45.4503
5.0E+08	0.471795	-62.3880	4.057046E-02	38.2308	9.62995	125.781	0.633146	-51.7704
6.0E+08	0.421506	-69.3569	4.316292E-02	33.3405	8.53559	120.378	0.570209	-56.7206
7.0E+08	0.379961	-75.2612	4.499071E-02	29.4764	7.62375	116.005	0.518803	-60.6598
8.0E+08	0.345693	-80.3608	4.631140E-02	26.3755	6.86423	112.398	0.476987	-63.8540

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$V_{CE} = 5V$ and $I_C = 10mA$ (Continued)

FREQ. (Hz)	S ₁₁	PHASE(S ₁₁)	S ₁₂	PHASE(S ₁₂)	S ₂₁	PHASE(S ₂₁)	S ₂₂	PHASE(S ₂₂)
1.0E+08	0.728106	-16.4319	1.273920E-02	75.4177	15.1273	165.227	0.959692	-14.2688
9.0E+08	0.317301	-84.8420	4.728948E-02	23.8481	6.22797	109.365	0.442915	-66.4948
1.0E+09	0.293608	-88.8381	4.803091E-02	21.7581	5.69057	106.771	0.415044	-68.7193
1.1E+09	0.273680	-92.4452	4.860515E-02	20.0070	5.23257	104.518	0.392146	-70.6269
1.2E+09	0.256782	-95.7336	4.905871E-02	18.5224	4.83873	102.532	0.373261	-72.2899
1.3E+09	0.242344	-98.7555	4.942344E-02	17.2505	4.49716	100.759	0.357640	-73.7620
1.4E+09	0.229918	-101.551	4.972158E-02	16.1506	4.19854	99.1602	0.344698	-75.0832
1.5E+09	0.219152	-104.150	4.996903E-02	15.1915	3.93554	97.7028	0.333974	-76.2840
1.6E+09	0.209767	-106.577	5.017730E-02	14.3490	3.70234	96.3629	0.325102	-77.3877
1.7E+09	0.201539	-108.851	5.035491E-02	13.6040	3.49428	95.1215	0.317789	-78.4122
1.8E+09	0.194288	-110.988	5.050825E-02	12.9411	3.30758	93.9633	0.311800	-79.3715
1.9E+09	0.187867	-113.001	5.064218E-02	12.3482	3.13919	92.8761	0.306940	-80.2768
2.0E+09	0.182157	-114.902	5.076045E-02	11.8151	2.98658	91.8500	0.303051	-81.1365
2.1E+09	0.177056	-116.698	5.086598E-02	11.3338	2.84766	90.8766	0.300003	-81.9578
2.2E+09	0.172484	-118.399	5.096107E-02	10.8974	2.72068	89.9494	0.297686	-82.7460
2.3E+09	0.168370	-120.012	5.104755E-02	10.5001	2.60420	89.0626	0.296007	-83.5057
2.4E+09	0.164656	-121.542	5.112690E-02	10.1373	2.49697	88.2115	0.294889	-84.2405
2.5E+09	0.161293	-122.996	5.120031E-02	9.80479	2.39793	87.3920	0.294266	-84.9533
2.6E+09	0.158239	-124.378	5.126876E-02	9.49919	2.30619	86.6007	0.294081	-85.6466
2.7E+09	0.155458	-125.694	5.133304E-02	9.21750	2.22098	85.8348	0.294285	-86.3223
2.8E+09	0.152919	-126.947	5.139381E-02	8.95716	2.14162	85.0916	0.294836	-86.9822
2.9E+09	0.150595	-128.140	5.145164E-02	8.71595	2.06753	84.3690	0.295696	-87.6275
3.0E+09	0.148463	-129.279	5.150697E-02	8.49194	1.99820	83.6651	0.296834	-88.2595

Typical Performance Curves

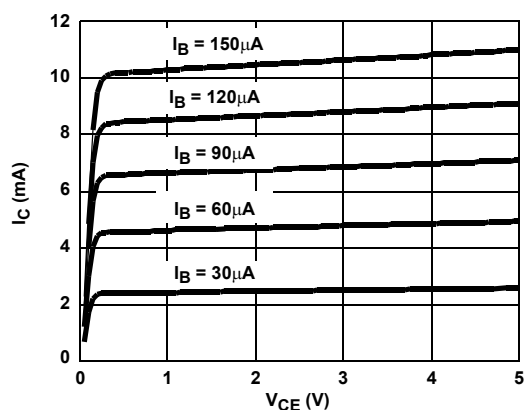


FIGURE 1. I_C vs V_{CE}

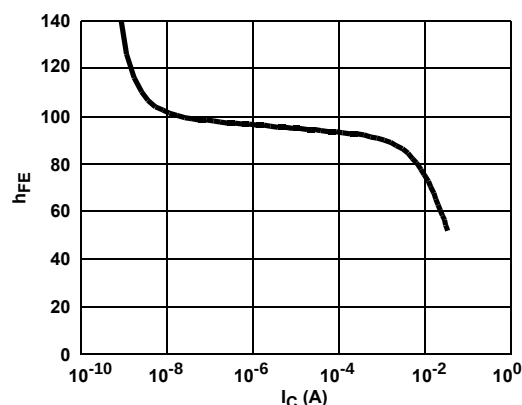


FIGURE 2. h_{FE} vs I_C

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Typical Performance Curves (Continued)

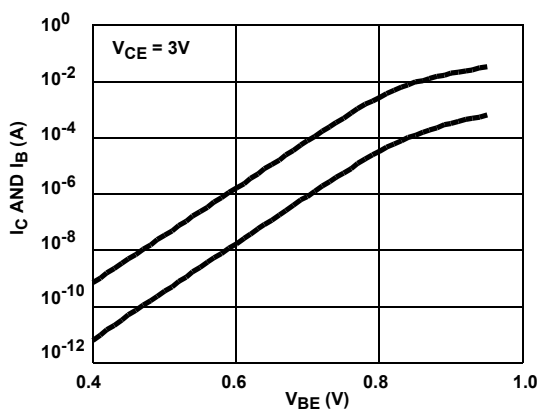


FIGURE 3. GUMMEL PLOT

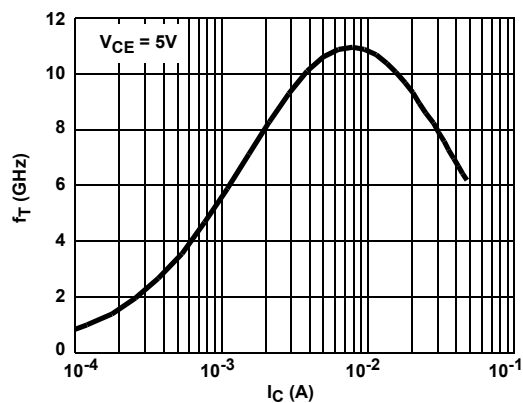


FIGURE 4. f_T vs I_C

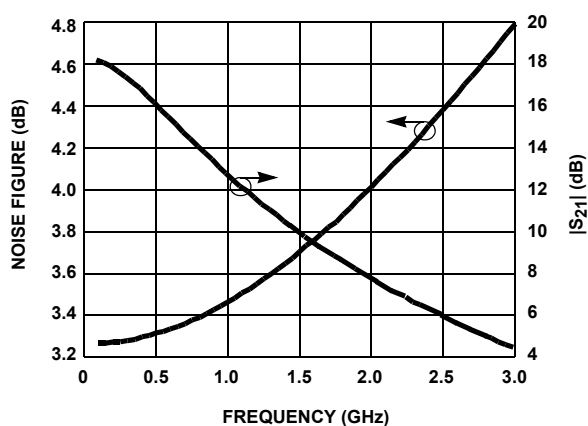


FIGURE 5. GAIN AND NOISE FIGURE vs FREQUENCY

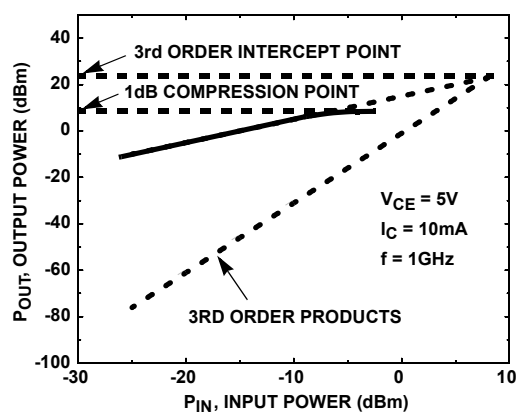


FIGURE 6. P_{1dB} AND 3RD ORDER INTERCEPT

HFA3102

Die Characteristics

PROCESS:

UHF-1

DIE DIMENSIONS:

53 mils x 52 mils x 14 mils
1340 μ m x 1320 μ m x 355.6 μ m

METALLIZATION:

Type: Metal 1: AlCu(2%)/TiW
Thickness: Metal 1: 8k $\text{\AA}$ $\pm$ 0.5k $\text{\AA}$
Type: Metal 2: AlCu(2%)
Thickness: Metal 2: 16k $\text{\AA}$ $\pm$ 0.8k $\text{\AA}$

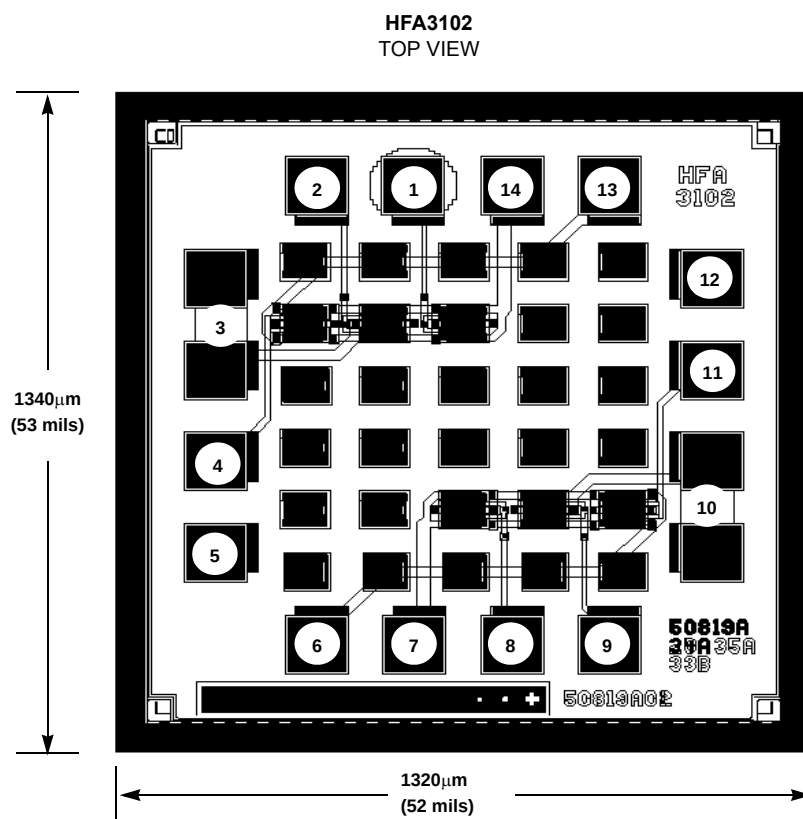
PASSIVATION:

Type: Nitride
Thickness: 4k $\text{\AA}$ $\pm$ 0.5k $\text{\AA}$

SUBSTRATE POTENTIAL (POWERED UP):

Floating

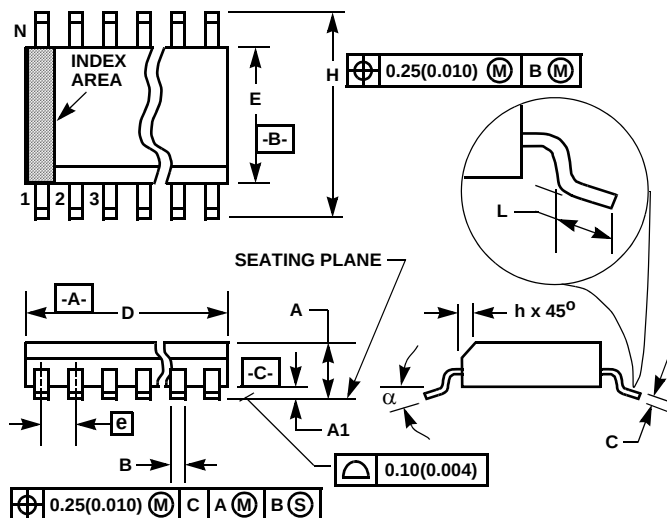
Metallization Mask Layout



Pad numbers correspond to the 14 pin SOIC pinout.

HFA3102

Small Outline Plastic Packages (SOIC)



NOTES:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- "L" is the length of terminal for soldering to a substrate.
- "N" is the number of terminal positions.
- Terminal numbers are shown for reference only.
- The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
- Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M14.15 (JEDEC MS-012-AB ISSUE C) 14 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
B	0.013	0.020	0.33	0.51	9
C	0.0075	0.0098	0.19	0.25	-
D	0.3367	0.3444	8.55	8.75	3
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	14		14		7
α	0°	8°	0°	8°	-

Rev. 0 12/93

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Intersil Corporation's quality certifications can be viewed at www.intersil.com/design/quality

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